

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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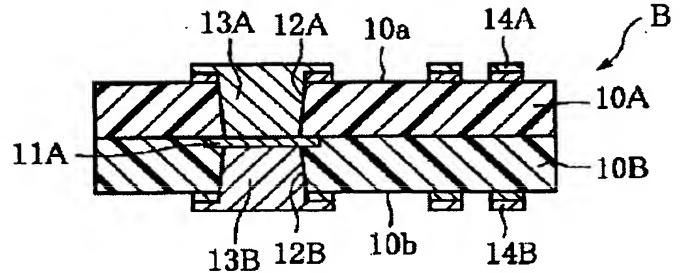
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TITLE : CORE SUBSTRATE AND MULTILAYER  
CIRCUIT BOARD USING THE SAME



**ABSTRACT :** PROBLEM TO BE SOLVED: To provide a core substrate being useful for manufacturing a multilayer circuit board, that can achieve low resistance and fine patterns, since the interlayer connection of an entire layer can be made by series structure formed by an electrical copper-plated member.

**SOLUTION:** In a core substrate that has a plurality of unit circuit substrates laminated on the upper and lower surfaces and is used for manufacturing a multilayer circuit board, a conductor land section 11A is pinched for laminating insulating layers 10A and 10B, a pair of laser machining holes 12A and 12B which are extended to a conductor land section 11A from surfaces 10a and 10b of the insulating layer is formed on the upper and lower sections of the conductor land section 11A, and an electric plated member is filled into each of the pair of laser machining holes for forming a pair of columnar conductors 13A and 13B, connected electrically via the conductor land section 11A.

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